APPLICA	BLE STAN	DARD								
OPERATING					STORAGE	PRAGE  MPERATURE RANGE -1		-10°C TO + 60°C (NOTE3)		
DATING	TEMPERATURE RANGE OPERATING				STORAGE		+			· /
RATING	HUMIDITY RANGE		20 % TO 80 %(NO	ITEZ)	HUMIDITY R		-	40 % TO 70 % (NOTE3		
	VOLTAGE		AC/DC 100V		CONNECTO	R		DF50A-*S-1C		
	CURRENT		AWG 28 : 1.0		APPLICABI CONTACT	LE		DF50-2830SCF	-A	
			AWG 30 : 0.9							
				CIFICA	<u>HONS</u>					
	EM		TEST METHOD			R	EQUIF	REMENTS	QT	AT
GENERAL EX	RUCTION	TVICTIALLY	AND BY MEASI IDING INISTRI	IMENIT	IACCO	PDING TO		\\/\ING	X	
MARKING	AWINATION	VISUALLY AND BY MEASURING INSTRUMENT.  CONFIRMED VISUALLY.				ACCORDING TO DRAWING.				X
									Χ	
ELECTRIC CHARA CONTACT RESISTANCE					30mΩ ľ	30mΩ MAX.				Ι_
INSULATION	١	100V DC.			500MΩ	500MΩ MIN.				
RESISTANCE										_
VOLTAGE P	KOOF	300V AC FOR 1 min.			NO FLA	SHOVER	OR B	REAKDOWN.	X	-
MECHAN	NICAL CHA	ARACTI	ERISTICS						<u> </u>	1
MECHANIC	AL		INSERTIONS AND EXTRA	CTIONS.	① CO	NTACT R	ESIST	ANCE: 50mΩ MAX.		
OPERATION						② NO DAMAGE, CRACK OR LOOSENESS				_
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE				OF PARTS.  ① NO ELECTRICAL DISCONTINUITY OF 1μs.				
		0.75 mm, AT 10 CYCLE FOR EACH, FOR 3			② NO	2 NO DAMAGE, CRACK OR LOOSENESS X -				_
SHOCK		DIRECTIONS.  490 m/s <sup>2</sup> DURATION OF PULSE 11 ms				PARTS.				
OHOOK		1	ES FOR 3 DIRECTIONS.	1113						
ENVIRO	NMENTAL	CHAR	ACTERISTICS							
DAMP HEAT		EXPOSE	D AT 40 ± 2 °C, 90 TO 95 9	%, 96 h.	1 -			ANCE: 50mΩ MAX.		
(STEADY STATE)						② INSULATION RESISTANCE: 100MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS				-
						PARTS.	E, CRA	ICK OR LOOSENESS		
RAPID CHA		TEMPERATURE -55→+85°C TIME 30→ 30min. UNDER 5 CYCLES. THE TRANSFERRING TIME OF THE TANK			1 -	① CONTACT RESISTANCE: 50mΩ MAX.			Х	
TEMPERAT	JRE					<ul><li>② INSULATION RESISTANCE: 500MΩ MIN.</li><li>③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li></ul>				_
					I					
		IS 2∼3 m	nin.							
COUN	T D	 	ON OF REVISIONS		ESIGNED			CHECKED	D/	ATE
A	·   D	LOUINIF III	OIT OF INEVIOUNS		LOIGINED			OHLONED	"	
<u>-                                    </u>	I			I		APPRO\	/ED	KI. AKIYAMA	12.0	06. 26
						CHECK				06. 26
						DESIGN	-	ST. SATO		
						DRAW		ST. SATO	+	06. 26
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			est	DRAWIN	FI 04 040F7					
								)F50A-*P-1H(51)	- 01	
			TOTALISM STILL						<u> </u>	
		OSE EI	LECTRIC CO., LTD.	С	ODE NO.	o.   CL665-		CL665-	Δ	1/2

TEST METHOD SOLDERED AT SOLDER TEMPERATURE, 245°C FOR INSERTION DURATION, 5 sec.	REQUIREMENTS SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	QT	АТ
	100 70 ST THE GOTT FIGURE BEING HAIMEROED.	×	_
1) REFLOW SOLDERING  «REFLOW AREA»  MAX250°C WITHIN 10 sec  MIN 220°C WITHIN 60 sec  «PREHEATING AREA»  150~180°C 90~120s  2) MANUAL SOLDERING  SOLDERING IPON TEMPERRATURE 350±10°C  SOLDERING TIME 3~4s.  NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	_
	MIN 220°C WITHIN 60 sec  《PREHEATING AREA》  150~180°C 90~120s 2) MANUAL SOLDERING  SOLDERING IPON TEMPERRATURE 350±10°C  SOLDERING TIME 3~4s.	MIN 220°C WITHIN 60 sec  《PREHEATING AREA》  150~180°C 90~120s  2) MANUAL SOLDERING  SOLDERING IPON TEMPERRATURE 350±10°C  SOLDERING TIME 3~4s.	MIN 220°C WITHIN 60 sec  《PREHEATING AREA》  150~180°C 90~120s  2) MANUAL SOLDERING  SOLDERING IPON TEMPERRATURE 350±10°C  SOLDERING TIME 3~4s.

## REMARKS

NOTE 1: INCLUDING THE TEMPERATURE RISE BY CURRENT.

NOTE 1: INCLUDING THE TEMPERATURE RISE BY CORRENT.

NOTE 2: NON-CONDENSING

NOTE 3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD.

AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION

Unless otherwise specifid, refer to JIS C 5402.

Note QT:Q	ualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.		ELC4-346572-01		
HRS	SPECIFICATION SHEET	PART NO.	DF50A-*P-1H(51)			
	HIROSE ELECTRIC CO., LTD.	CODE NO		CL665-	<b>A</b>	2/2